Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 - 15 (Canceled)

16. (New) A composition for cleaning a semiconductor substrate, the composition comprising:

a fluoride containing compound selected from a fluoroboric acid; a compound of the general formula R₁R₂R₃R₄NF, where R₁, R₂, R₃ and R₄ are independently hydrogen, an alcohol group, an alkoxy group or an alkyl group; and mixtures thereof,

a buffer comprising an acid selected from a weak acid and a protonated base and a base selected from the group consisting of an amine, ammonia, ammonium hydroxide and an alkyl ammonium hydroxide in a molar ratio of the acid to the base that is substantially 1:1, and

optionally an organic polar solvent wherein the solvent is miscible in water wherein the composition has a pH that ranges from greater than 7.0 to about 11.0.

- 17. (New) The composition of claim 16 further comprising a corrosion inhibitor.
- 18. (New) The composition of claim 16 wherein the fluoride containing compound is the compound of the general formula $R_1R_2R_3R_4NF$.
- 19. (New) The composition of claim 18 wherein the compound is ammonium fluoride, tetramethyl ammonium fluoride, or tetraethyl ammonium fluoride.

- (New) The composition of claim 16 wherein the buffer comprises the weak acid selected 20. from abietic acid, aspartic diamide, aspidospermine, N,N-bis(2-hydroxylethel)-2-aminoethane sulfonic acid, 4-chloro-2-(2'-thiazolylazo)phenol, chrome dark blue, diacetylacetone, 5,5diallybarbituric acid, 1,3-dichloro-2,5-dihydroxybenzene, 2,3-dichlorophenol, 3,4dihydroxybenzaldehyde, 2,6-dihydroxypurine, 1,10-dimethoxy-3,8-dimethyl-4,7-phenanthroline, N,N'-dimethylethylenediamine-N,N'-diacetic acid, dimethylhydroxytectracycline, 2,6-dimethyl-4nitrophenol, ethyl-2-mercaptoacetate, 5-ethyl-5-pentylbarbituric acid, 5-ethyl-5-phenylbarbituric acid, glycine hydroxamic acid, hexamethyldisilazane, 1,2,3,8,9,10-hexamehtyl-4,7phenathroline, 4-hydroxybenzaldehyde, 4-hydroxybenzonitrile (4-cyanophenol), 10hydroxycodeine, N-(2-hydroxyehtyl)piperazine-N'-ethansulfonic acid ("HEPES"), 5-hydroxy-2-(hydroxymethyl)-4H-pyran-4-one, 2-hydroxy-3-methoxybenzaldehyde, 4-hydroxy-3methoxybenzaldehyde, 3-hydroxy-4-nitrotoluene,4-methoxy-2-(2'-thiazoylazo)phenol, 2,2'methylenebis(4-chlorophenol), 4-(methylsulfonyl)phenol, methylthioglycolic acid, 1methylxanthine, 3-(N-morpholino)propanesulfonic acid, 2-nitrohydroquinone, 2-nitrophenol, 4nitrophenol, 2-nitropropane, phenosulsulfonepthalein, 3-pheny-α-analine methyl ester, pyrocatecholsulfonepthelein, sylvic acid, 1,3,5-triazine-2,4,6-triol, 2,4,5-trichlorophenol, 3,4,5trichlorophenol, 2-[tris(hydroxymethyl)methylamineo]-1]ethansulfonic acid, tyrosine amide, tyrosine ethyl ester, uridine-5-diphosphoric acid and benzotriazole.
- 21. (New) The composition of Claim 20 wherein the weak acid is HEPES, benzotriazole or vanillin.
- 22. (New) The composition of claim 16 wherein the buffer comprises the protonated base selected from alanine methyl ester, 2-aminoacetamide, 4-amino-3-bromomethylpyridine, 2-aminobutanoic acid methyl ester, 1-aminoisoquinoline, 4-aminoisoxazolidine-3-one, 2-amino-3-methylpyridine, 2-amino-4-methylpyridine, 2-amino-5-methylpyridine, 2-amino-6-methylpyridine,

2-aminoquilone, n-tert-butanaline, codeine, 2-cyanoethylamine, 2-cyclohexyl-2-pyrroline, N,N-diethyl-o-toluidine, dihydroergonovine, N,N'-dimethyl-p-toluidine, emetine, ergometrinine, 2-ethyl-2-pyrroline, N-ethylveratramine, glycine ethyl ester, glycine methyl ester, glyoxaline, harmine, heroin, isopilocarpine, leucine amide, leucine ethyl seater, methoxycarbonylmethylamine, 1-methylimidazole, 4-methylimidazole, N-methylmorpholine, morphine, N-pentylveratriamine, N-propylveratriamine, serine methyl ester, solanine, 2,3,5,6-tetramethylpyridine, thebaine, 3-thio-S-methylcarbizide, triethanolamine, 2,3,6-trimethylpyridine, 2,4,6-trimethylpyridine, tris(2-hydroxyethyl)amine, L-valine methyl ester, vetramine, and vitamin B₁₂.

- 23. (New) The composition of Claim 16 comprising an organic, polar solvent.
- 24. (New) The composition of Claim 23 wherein the solvent is one selected from an amine, a sulfoxide, a sulfone, an amide, a lactone, a pyrrolidone, an imidazolidinone, a glycol ether and mixtures thereof.
- 25. (New) The composition of Claim 23 wherein the solvent is dimethylacetamide.
- 26. (New) The composition of Claim 23 wherein the solvent is N-methylpyrrolidone.
- 27. (New) The composition of Claim 16 wherein the pH ranges from greater than 7.0 to about 9.0.
- 28. (New) The composition of Claim 27 wherein the pH ranges from greater than 7.0 to about 8.4.

29. (New) An aqueous, buffered fluoride-containing composition, comprising;

from 0.1% by weight to 20% by weight of a fluoride containing compound selected from fluoroboric acid; a compound of the general formula $R_1R_2R_3R_4NF$, where R_1,R_2,R_3 and R_4 are independently hydrogen, an alcohol group or an alkyl group; and mixtures thereof,

up to 70% by weight of an organic polar solvent wherein the solvent is miscible in water a buffer comprising an acid selected from a weak acid and a protonated base and a base selected from the group consisting of an amine, ammonia, ammonium hydroxide and an alkyl ammonium hydroxide in a molar ratio of the acid to the base that is substantially 1:1, and

wherein the aqueous, buffered, fluoride containing composition has a pH that ranges from greater than 7.0 to about 11.0.

from 1% by weight to 92% by weight water,

- 30. (New) The aqueous, buffered, fluoride containing composition of Claim 29 wherein the water is present in amounts ranging from 1% by weight to 70% by weight.
- 31. (New) A method of stabilizing oxide and metallic etch rates of an aqueous, fluoride containing composition, the method comprising:

providing the composition comprising a fluoride containing compound selected from fluoroboric acid; a compound of the general formula $R_1R_2R_3R_4NF$, where R_1,R_2,R_3 and R_4 are independently hydrogen, an alcohol group or an alkyl group; and mixtures thereof; and an organic polar solvent;

adding a buffer to the composition to adjust the pH of the composition to a range of from greater than 7.0 to about 11.0 wherein the buffer comprises an acid selected from a weak acid and a protonated base and a base selected from the group consisting of an amine, ammonia, ammonium hydroxide and an alkyl ammonium hydroxide in a molar ratio of the acid to the base that is substantially 1:1.